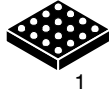


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

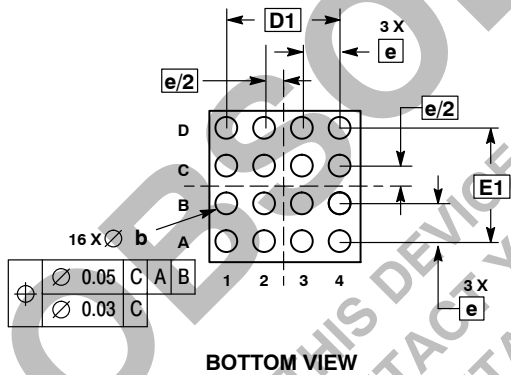
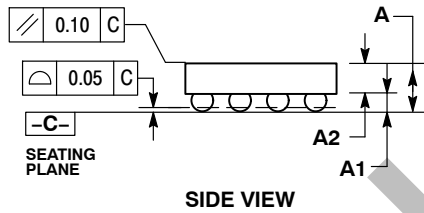
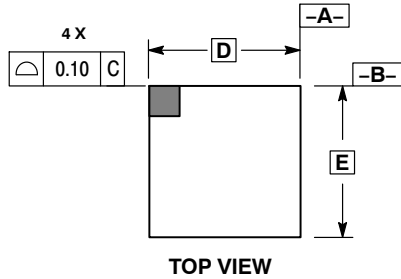
ON Semiconductor®



SCALE 4:1

16 PIN FLIP-CHIP
CASE 499AN
ISSUE A

DATE 18 NOV 2019



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	2.000 BSC	
E	2.000 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.500 BSC	
E1	1.500 BSC	

THIS DEVICE IS OBSOLETE
PLEASE CONTACT YOUR ON SEMICONDUCTOR REPRESENTATIVE FOR INFORMATION

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	16 PIN FLIP-CHIP, 2.00 X 2.00 MM	PAGE 1 OF 2

